IN THE SPECIFICATION:

Please replace paragraph [021] at page 5, with the following amended paragraph:

-- In accordance with Fig. 1, an LED die 3 ($R_{th, LED\ die}$) is applied to a contact surface (e.g. conductor path 5) of an LED PCB 6 ($R_{th, LED\ PCB}$) by means of a die adhesive 4. The LED die 3 in Fig. 1 is mounted face up and connected via bonding wires 2 with the contact surfaces (conductor path 5). Alternatively thereto, this can also be arranged in a face down mounting directly on the LED PCB 6 or this can be attached face down to a die carrier, and the latter then arranged on the LED PCB. For example, Fig. 4 shows the LED die 3 mounted face down onto LED PCB 6 by means of die attach 4. The LED PCB 6 has at its underside rear side contacts 7. The rear side contacts 7 of the LED PCB 6 at least partially cover over the LED PCB 6, and may cover over at least the half area of the LED PCB 6, or cover the entire area of the LED PCB 6 apart from at least one exception. Together with the rear side contacts 7 ($R_{th, solder\ pads}$) of the LED PCB 6 ~~this arrangement represents~~ these arrangements represent a self-contained LED lamp. Also, as shown in Fig. 4, the LED PCB 6 includes a plurality of conductive through-vias 13, which thermally and electrically connect the rear side contacts 7 of the LED PCB 6 to contact areas formed on an upper side of the LED PCB 6. For further processing, this LED lamp can be assembled by means of a mounting technology (e.g. SMT) on a board 9 ($R_{th, board}$), which is then 15 optionally connected with a cooling body 11, e.g. via a solder area 10 ($R_{th, solder\ area}$). For example, in the embodiment shown in Fig. 4, the LED lamp is arranged on the additional board 9, which includes on an upper side thereof, contact areas 8. The contact areas 8 may be soldered to the rear side contacts 7 of the LED PCB 6. The additional board 9 also includes conductive through-vias 13 in the additional board 9. The conductive through-vias 13 in the additional board 9 thermally and electrically connect at least one of the contact areas 8 of the additional board 9 to a solder area formed at an underside of the additional board 9.--